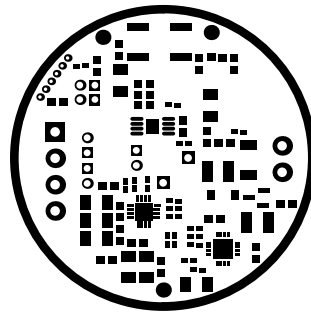
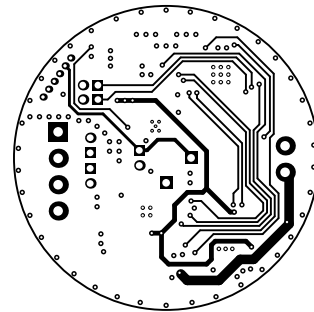


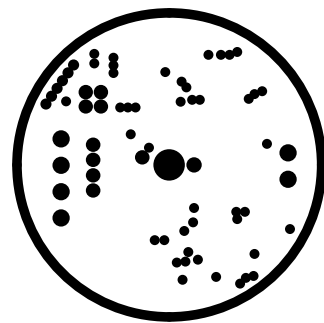
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2/5/2014	1:51:30 PM	TEXAS INSTRUMENTS



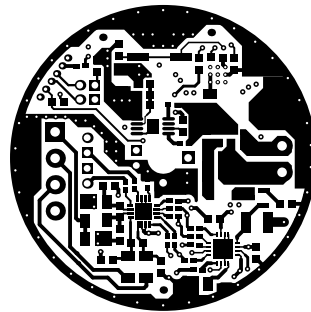
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/5/2014 1:51:31 PM	TEXAS INSTRUMENTS	



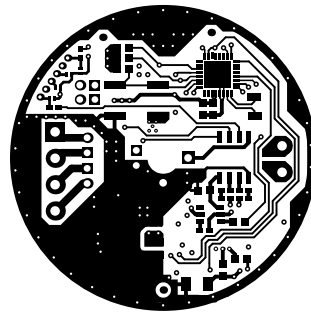
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Top Board Outline			
PLOT NAME = Inner 1	GENERATED : 2/5/2014 1:51:31 PM	TEXAS INSTRUMENTS	



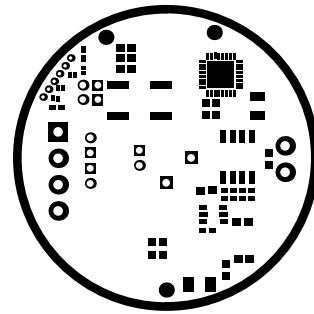
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LAYER NAME = GNDBoard Outline			
PLOT NAME = GND	GENERATED : 2/5/2014 1:51:32 PM	TEXAS INSTRUMENTS	



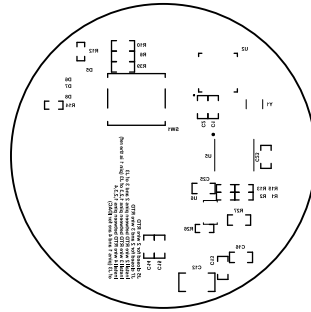
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/5/2014 1:51:33 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/5/2014 1:51:33 PM	TEXAS INSTRUMENTS	



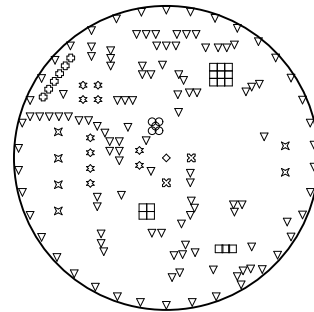
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/5/2014 1:51:34 PM	TEXAS INSTRUMENTS	



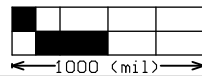
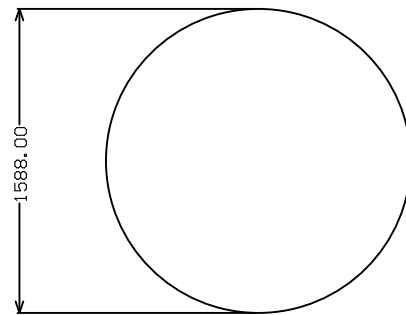
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 2/5/2014 1:51:34 PM	TEXAS INSTRUMENTS	

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	5	7.874mil (0.2mm)	PTH	Round
□	16	11.811mil (0.3mm)	PTH	Round
▽	120	12mil (0.305mm)	PTH	Round
⊕	6	18mil (0.457mm)	PTH	Round
*	10	35mil (0.889mm)	PTH	Round
⊗	2	40mil (1.016mm)	PTH	Round
⊗	6	50mil (1.27mm)	PTH	Round
◇	1	125mil (3.175mm)	PTH	Round
	166 Total			

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/5/2014	1:51:35 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/5/2014 1:51:36 PM	TEXAS INSTRUMENTS	

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